Product Preview

IGBT with Monolithic Free Wheeling Diode

This Insulated Gate Bipolar Transistor (IGBT) features a robust and cost effective ultra Field Stop (FS) Trench construction and provides superior performance. It is especially designed for low on–state and is well suited for resonant or soft switching topologies, such as those used in inductive heating applications. The device contains a reverse conducting diode integrated on the same die, which makes the device construction very cost effective.

Features

- Extremely Efficient Trench with Ultra Field Stop Technology
- 1400 V Breakdown Voltage
- Optimized for Low Losses in IH Cooker Application
- Reliable and Cost Effective Single Die Solution
- These are Pb-Free Devices

Typical Applications

- Inductive Heating
- Consumer Appliances
- Soft Switching

ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-emitter voltage @ T _J = 25°C	V _{CES}	1400	V
Collector current @ Tc = 25°C @ Tc = 100°C	<u>_</u> C	60 30	А
Pulsed collector current, T_{pulse} limited by T_{Jmax} 10 μs pulse, V_{GE} = 15 V	Ісм	120	А
Diode forward current @ Tc = 25°C @ Tc = 100°C	l _F	60 30	Α
Diode pulsed current, T_{pulse} limited by T_{Jmax} 10 μs pulse, V_{GE} = 0 V	I _{FM}	120	Α
Gate-emitter voltage Transient Gate-emitter Voltage (T _{pulse} = 5 μs, D < 0.10)	$V_{\sf GE}$	±20 ±25	V
Power Dissipation @ Tc = 25°C @ Tc = 100°C	P _D	357 178	W
Operating junction temperature range	T_J	-40 to +175	°C
Storage temperature range	T _{stg}	-55 to +175	°C
Lead temperature for soldering, 1/8" from case for 5 seconds	T _{SLD}	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

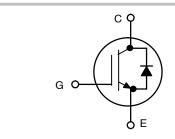
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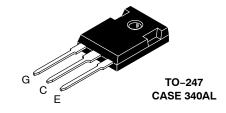


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30 A, 1400 V V_{CEsat} = 1.8 V E_{off} = 1.05 mJ





MARKING DIAGRAM



A = Assembly Location

Y = Year WW = Work Week G = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping
NGTB30N140IHR3WG	TO-247 (Pb-Free)	30 Units / Rail

THERMAL CHARACTERISTICS

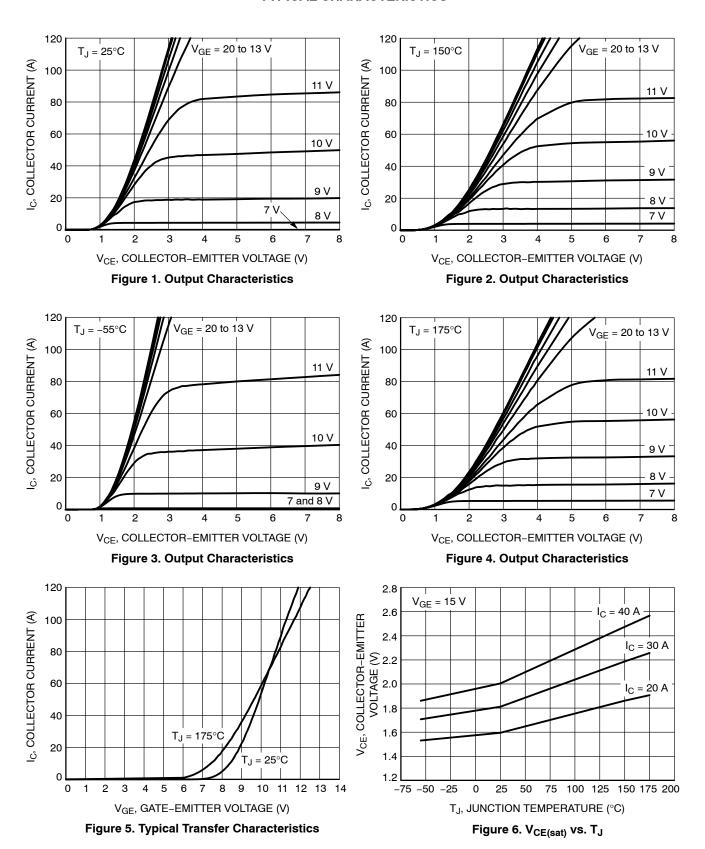
Rating	Symbol	Value	Unit
Thermal resistance junction-to-case	$R_{ heta JC}$	0.7	°C/W
Thermal resistance junction-to-ambient	$R_{ hetaJA}$	40	°C/W

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
STATIC CHARACTERISTIC				•	-	
Collector-emitter breakdown voltage, gate-emitter short-circuited	V _{GE} = 0 V, I _C = 1 mA	V _{(BR)CES}	1400	_	-	V
Collector-emitter saturation voltage	V _{GE} = 15 V, I _C = 30 A V _{GE} = 15 V, I _C = 30 A, T _J = 175°C	V _{CEsat}	-	1.80 2.20	1.95 -	V
Gate-emitter threshold voltage	$V_{GE} = V_{CE}, I_{C} = 175 \mu A$	V _{GE(th)}	4.5	5.7	6.5	V
Collector-emitter cut-off current, gate- emitter short-circuited	V _{GE} = 0 V, V _{CE} = 1400 V V _{GE} = 0 V, V _{CE} = 1400 V, T _{J =} 175°C	I _{CES}	- -	_ 210	20 -	μΑ
Gate leakage current, collector-emitter short-circuited	V _{GE} = 20 V, V _{CE} = 0 V	I _{GES}	-	_	120	nA
DYNAMIC CHARACTERISTIC						
Input capacitance		C _{ies}	-	3505	_	pF
Output capacitance	V _{CE} = 20 V, V _{GE} = 0 V, f = 1 MHz	C _{oes}	-	70	-	
Reverse transfer capacitance		C _{res}	-	58	-	
Gate charge total		Q_g	-	163	-	nC
Gate to emitter charge	V_{CE} = 600 V, I_{C} = 30 A, V_{GE} = 15 V	Q _{ge}	-	30	-	
Gate to collector charge		Q _{gc}	-	81	_	
SWITCHING CHARACTERISTIC, INDUCT	IVE LOAD					
Turn-off delay time	$T_J = 25^{\circ}\text{C}, V_{CC} = 600 \text{ V}, \\ I_C = 30 \text{ A}, R_g = 10 \Omega \\ V_{GE} = -1.5 \text{V to } +15 \text{ V}$	t _{d(off)}	-	197	_	ns
Fall time		t _f	-	122	-	
Turn-off switching loss		E _{off}	-	1.05	_	mJ
Turn-off delay time	T_J = 150°C, V_{CC} = 600 V, I_C = 30 A, R_g = 10 Ω V_{GE} = 15 V	t _{d(off)}	-	209	_	ns
Fall time		t _f	-	214	-	
Turn-off switching loss	V _{GE} = 15 V	E _{off}	-	1.75	-	mJ
DIODE CHARACTERISTIC						
Forward voltage	$V_{GE} = 0 \text{ V}, I_F = 30 \text{ A}$ $V_{GE} = 0 \text{ V}, I_F = 30 \text{ A}, T_J = 175^{\circ}\text{C}$	V _F	- -	1.90 2.48	2.10 -	V

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS

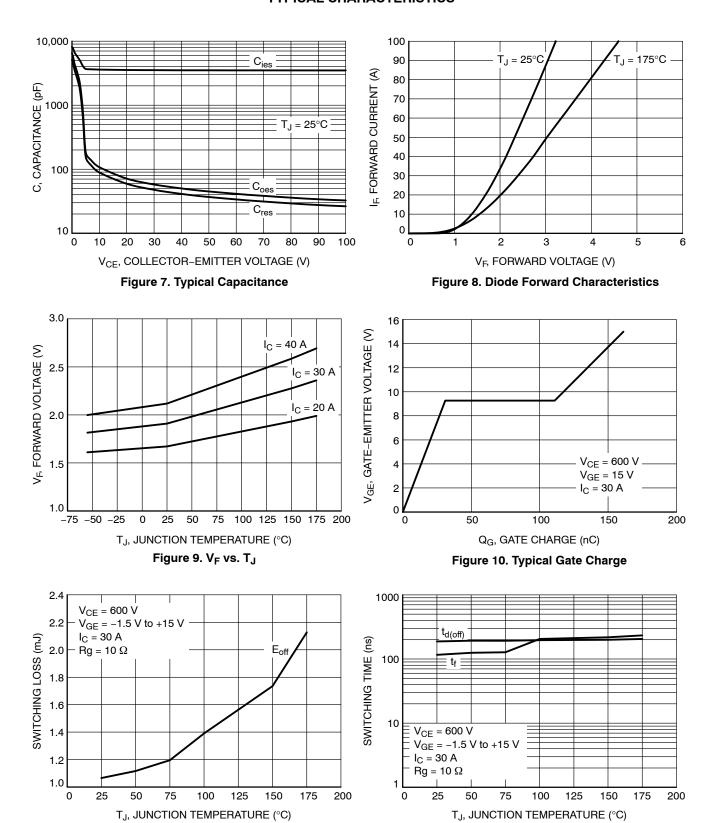


Figure 12. Switching Loss vs. Temperature

Figure 11. Switching Loss vs. Temperature

TYPICAL CHARACTERISTICS

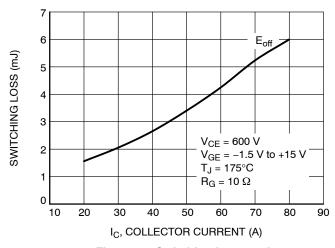


Figure 13. Switching Loss vs. I_C

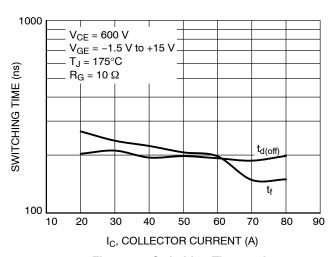


Figure 14. Switching Time vs. I_C

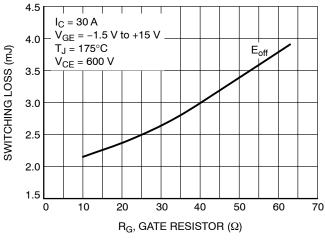


Figure 15. Switching Loss vs. I_C

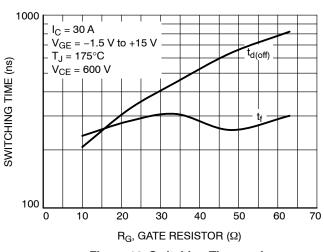


Figure 16. Switching Time vs. I_C

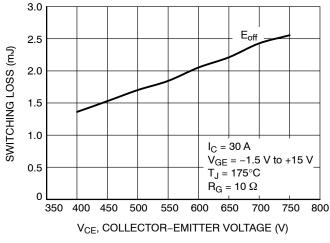


Figure 17. Switching Loss vs. I_C

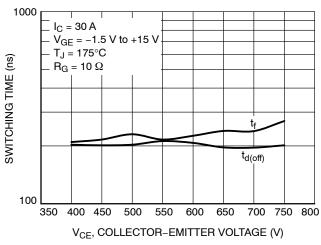
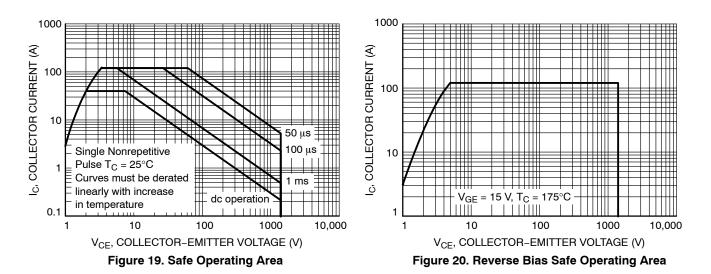


Figure 18. Switching Time vs. I_C

TYPICAL CHARACTERISTICS



 $R_{\theta JC} = 0.42$ R(t), SQUARE-WAVE PEAK (°C/W) 50% Duty Cycle 20% 0.1 10% 5% R₂ Junction R₁ Case R_i (°C/W) 2% 0.1063 0.01 0.0566 0.0177 $C_i = \tau_i / R_i$ 0.1189 0.0841 C_1 C_2 C_n 0.001 0.0005 220.8521 Duty Factor = t_1/t_2 Peak $T_J = P_{DM} \times Z_{\theta JC} + T_C$ Single Pulse 0.0001 0.000001 0.00001 0.0001 0.001 0.01 0.1 ON-PULSE WIDTH (s)

Figure 21. IGBT Transient Thermal Impedance

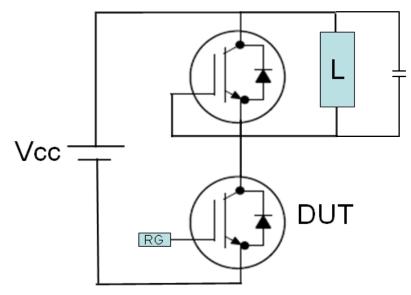


Figure 22. Test Circuit for Switching Characteristics

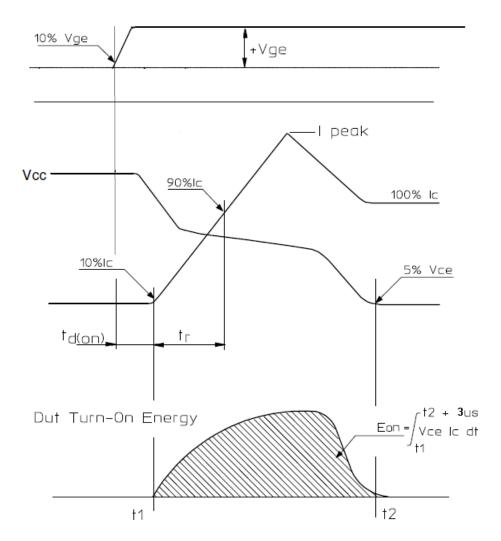


Figure 23. Definition of Turn On Waveform

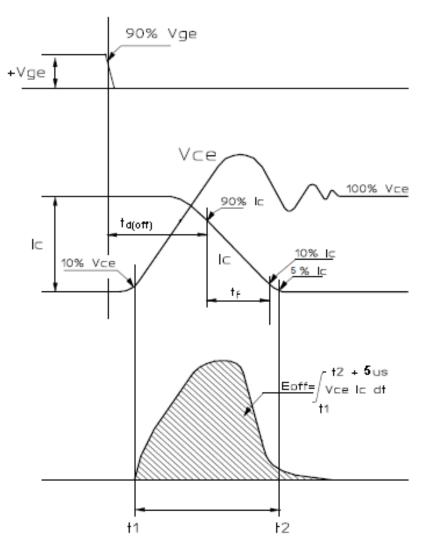
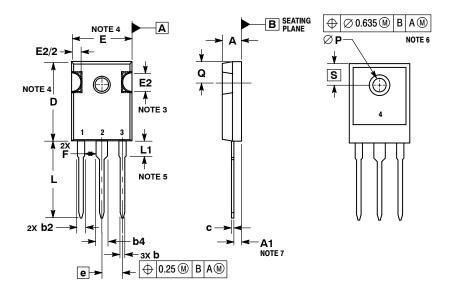


Figure 24. Definition of Turn Off Waveform

PACKAGE DIMENSIONS

TO-247 CASE 340AL ISSUE D



- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

- DIMENSIONING AND TOLEHANCING PEH ASME Y14.5M, 18 CONTROLLING DIMENSION: MILLIMETERS. SLOT REQUIRED, NOTCH MAY BE ROUNDED. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.13 PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST PORTION. EXTREME OF THE PLASTIC BODY.
- LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY
- ØP SHALL HAVE A MAXIMUM DRAFT ANGLE OF 1.5° TO THE TOP OF THE PART WITH A MAXIMUM DIAMETER OF 3.91.
 DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED

	MILLIMETERS		
DIM	MIN	MAX	
Α	4.70	5.30	
A1	2.20	2.60	
b	1.07	1.33	
b2	1.65	2.35	
b4	2.60	3.40	
С	0.45	0.68	
D	20.80	21.34	
E	15.50	16.25	
E2	4.32	5.49	
е	5.45 BSC		
F	2.655		
L	19.80	20.80	
L1	3.81	4.32	
P	3.55	3.65	
Q	5.40	6.20	
S	6.15 BSC		

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